

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER
TRANSMITTAL FORM

CFR 1.53(b)

Attorney Docket No. TI-26059

Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the
patent application of:

Inventor(s): Katherine G. Heinen
Darvin R. Edwards
Elizabeth G. Jacobs

"EXPRESS MAILING" Mailing Label No.
EE528827016US Date of Deposit November 5, 1998. I
hereby certify that this paper is being deposited with the
U.S. Postal Service Express Mail Post Office to Addressee
Service under 37 CFR 1.10 on the date shown above and is
addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231.

Lynne Van Deventer
Lynne Van Deventer

U.S. PTO
09/186973
11/05/98

For: Wafer-Scale Assembly of Chip-Size Packages

Enclosed are:

- 6 sheets of informal drawings and 20 pages of Specification (including Abstract)
x A Declaration/Power of Attorney
x Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 (e) (1) of provisional application number 60/066,256,
filed 11/20/97.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 790.00
Total Claims	18	-20 =	0	X \$22 =	\$0.00
Independent Claims	4	- 3 =	1	X \$82 =	\$82.00
Total Filing Fee					\$872.00

Please charge Deposit Account No. 20-0688 in the amount of the Total Fees set forth. The Commissioner is hereby
authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No.
20-0688. This form is submitted in triplicate.

All correspondence related to this application may be addressed to the undersigned at Klinger & Navarro, L.L.P. 801
E. Campbell Rd. Suite 655, RICHARDSON, TX 75081.

Date: November 5, 1998

Gary C. Hodeycutt
Gary C. Hodeycutt
Registration No. 20,250

09186973-110598

Specializing in Patents,
Trademarks, Copyrights
and other Intellectual
Property Matters

KLINGER & NAVARRO, L.L.P.

A Limited Liability Partnership
801 E. Campbell Road
Suite 655
Richardson, Texas 75081

(972) 238-7160 - Tel
(972) 238-7013 - Fax
navarro@kniplaw.com

November 5, 1998

VIA EXPRESS MAIL EE528827016US

Assistant Commissioner for Patents
Washington, D.C. 20231

Re: Patent Application For:
WAFER-SCALE ASSEMBLY OF CHIP-SIZE PACKAGES
Our File: 1000-2035

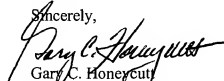
Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Original Patent Application and Drawings;
- (2) Original Assignment, Declaration, and Power of Attorney;
- (3) Assignment Recordation Form Cover sheet - Form PTO-1595;
- (4) Application Transmittal form; and
- (5) Postcards.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely,


Gary C. Honeycutt
Registration No. 20,250

GCH/lcv
Enclosure

cc: Warren Franz
E:\Honeycutt\Patents\1000-2035\Appl Cover page.WPD

09186973-110598